**Product End-of-Life Disassembly Instructions**

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

HP X24c Gaming Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 **Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main Board<em>1, Power Board</em>1, Key pad Board*1</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>HDMI cable*1</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
### Item Description | Notes | Quantity of items included in product
---|---|---
already listed as a separate item above) |  |  
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0  
Components and waste containing asbestos |  | 0  
Components, parts and materials containing refractory ceramic fibers |  | 0  
Components, parts and materials containing radioactive substances |  | 0  

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>Knife</td>
<td>1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Use screwdriver to remove two screws to unlock the base from the stand. Then remove four screws to unlock the stand from the monitor head.
2. Use knife to separate the back cover from the monitor head through the tear down slots which on the bottom side.
3. Remove the acetate tape (red frame) that fixes the wire and the isolation cover as shown in the figure, unplug the backlight (green frame), and then remove the aluminum foil (yellow frame) that fixes the wire and the shielding case.
4. Take the function key board out of the front frame, remove the tab on the function key board, and pull out the function key wire.
5. Remove three screws at the shielding case and pull out the wires.
6. Remove the LVDS cable (press the tabs on both sides and pull the LVDS cable upwards).
7. Remove the screws*11 fixing the front bezel and remove the mylar Tape.
8. Remove the screws at the mainboard interface.
9. Remove the screws at the powerboard to take off the myler. Then remove the screws*3 fixing the mainboard, screws*2 fixing the power board.
10. Disconnect the wire from mainboard and power board.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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EL-MF877-00  
Template Revision C  
Last revalidation date 09-May-2018  
HPI instructions for this template are available at EL-MF877-01
1. Use screwdriver to remove two screws to unlock the base from the stand. Then remove four screws to unlock the stand from the monitor head.

2. Use knife to separate the back cover from the monitor head through the tear down slots which on the bottom side.
3. Remove the acetate tape (red frame) that fixes the wire and the isolation cover as shown in the figure, unplug the backlight (green frame), and then remove the aluminum foil (yellow frame) that fixes the wire and the shielding case.

4. Take the function key board out of the front frame, remove the tab on the function key board, and pull out the function key wire.

5. Remove three screws at the shielding case and pull out the wires.

6. Remove the LVDS cable (press the tabs on both sides and pull the LVDS cable upwards).

HPI instructions for this template are available at [EL-MF877-01](#)
7. Remove the screws*11 fixing the front bezel and remove the mylar Tape.

8. Remove the screws at the mainboard interface.

9. Remove the screws at the powerboard to take off the myler. Then remove the screws*3 fixing the mainboard, screws*2 fixing the power board.

HPI instructions for this template are available at EL-MF877-01
10. Disconnect the wire from mainboard and power board.